

<b>Notice of References Cited</b>	Application/Control No. 09/873,021	Applicant(s)/Patent Under Reexamination NGUYEN ET AL.	
	Examiner Russell Frejd	Art Unit 2128	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	C	US-			
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**FOREIGN PATENT DOCUMENTS**

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**NON-PATENT DOCUMENTS**

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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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